

Please add the following new claims:

a²
-- 18. (New) The method of claim 1, further comprising introducing a photoimageable material layer, wherein the dielectric layer comprising the plurality of different material layers is introduced between the substrate and the photoimageable material layer.

~~19. (New) The method of claim 1, further comprising introducing an etch stop layer between the substrate and the dielectric layer comprising the plurality of different material layers.~~

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cs
20. (New) The method of claim 1, wherein the dielectric layer comprising the plurality of different material layers is introduced between an etch stop layer and a photoimageable material layer.

21. (New) The method of claim 8, further comprising introducing a photoimageable material layer, wherein the dielectric layer comprising the plurality of alternating material layers is introduced between the substrate and the photoimageable material layer.

~~22. (New) The method of claim 8, further comprising introducing an etch stop layer between the substrate and the dielectric layer comprising the plurality of alternating material layers.~~

23. (New) The method of claim 8, wherein the dielectric layer comprising the plurality of alternating material layers is introduced between an etch stop layer and a photoimageable material layer.--